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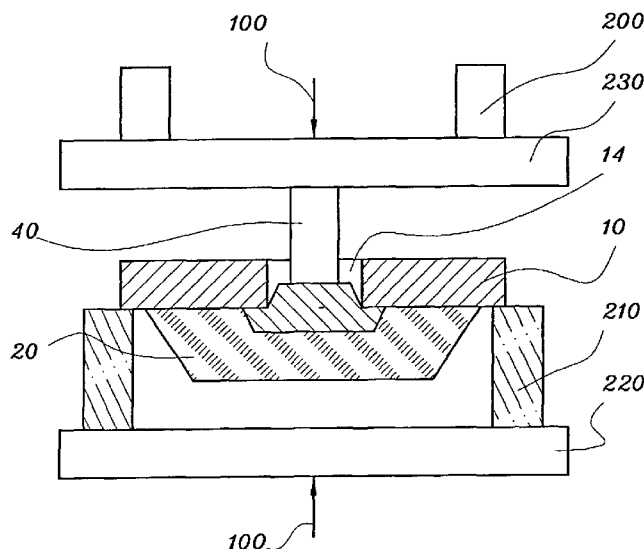
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(54) Title: APPARATUS AND METHOD FOR BONDING STRENGTH TESTING



(57) Abstract: An apparatus and a method for bonding strength testing, the apparatus comprises a substrate (10) and a test piece (20) adhered thereon. The substrate (10) has a first bonding portion (12), the test piece (20) has a second bonding portion (22) to bond onto the first bonding portion (12) of the substrate (10) to form a bonding interface, and a non-bonding portion (24) for receiving a test force (100) to separate the test piece (20) from the substrate (10). The test force (100) is applied perpendicular to the bonding interface; and the second bonding portion (22) and the non-bonding portion (24) face the same direction. The method comprises preparing a test piece (20) having a bonding portion (12) and a non-bonding portion (24); bonding the test piece (20) with the bonding portion (12) onto a substrate (10) to form a bonding interface, and applying a test force (100) perpendicular to the bonding interface onto the substrate (10) and the non-bonding portion (24) of the test piece (20) to break the bonding interface.